FORM PTO-1595 RE

HEET

U.S. DEPARTMENT OF COMMERC

Patent and Trademark Office

1-31-92 RE MINIMUM 101724				
To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.				
1. Name of conveying party(ies): Norihisa OKADA, Wataru KAWAMURA	2. Name and address of receiving party(ies): Name: Hitachi, Ltd.			
Additional name(s) of conveying party(ies) attached? Yes X No	Street Address: 6, Kanda Surugadai 4-chome,			
3. Nature of conveyance: Assignment	City: Tokyo:			
Security Agreement Change of Name Other	Country: Japan			
Execution Date: February 23, 2001	Additional name(s) & address(es) attached? Yes No			
4. Application number(s) or patent number(s):				
If this document is being filed together with a new application,	, the execution date of the application is: February 23, 2001			
A. Patent Application No.(s) 19/815055	B. Patent No.(s)			
	tached? 🔲 Yes 💢 No			
5. Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved: 1			
Name: ANTONELLI, TERRY, STOUT & KRAUS, LLP	7. Total fee (37 CFR 3.41)\$40.00			
Internal Address:	Enclosed Any deficiencies may be charged to deposit account Authorized to be charged to deposit account			
Street Address: 1300 North Seventeenth Street	8. Deposit account number: 01-2135			
Suite 1800 City: Arlington State: VA Zip: 22209	(Attach duplicate copy of this page if paying by deposit account)			
DO NOT US	E THIS SPACE			
9. Statement and signature. To the best of my knowledge and belief, the foregoing in of the original document.	formation is true and correct and any attached copy is a true copy			
Alan E. Schiavelli Name of Person Signing Attorney Registration No. 32,087 Total number of pages including cover sheet, attachments, and document:	March 14, 2001 Date			
OMB No. 0651-0011 (exp. 4/94)				

ASSIGNMENT (譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me or us citizen(s) of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

COMPOSITE PANEL AND BENDING PROCESSING METHOD OF THE SAME

invented by me or us and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

RECORDED: 03/14/2001

INVENTOR(S) (発明者フルネームサイン)			Date Signed (署名日)
1)	Norihisa OKADA	Northise Okada	2001.02,23:
2)	Wataru KAWAMURA	Wataru-Kawamura	7001.02.23
3)			
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PATENT REEL: 011819 FRAME: 0585